L Number	Hits	Search Text	DB	Time stamp
1	1	("6353267").PN.	USPAT	2002/06/30 00:11
2	1	("5989982").PN.	USPAT	2002/06/30 00:22
3	2	(("5994783") or ("6228681")).PN.	USPAT	2002/06/30 01:12
4	30128	device and (post or column or pillar) and (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 01:13
5	28848	(device and (post or column or pillar) and (bump or ball)) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:19
6	4679	((device and (post or column or pillar) and (bump or ball)) and (@ad<20010427)) and pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 01:15
7	566	((device and (post or column or pillar) and (bump or ball)) and (@ad<20010427)) and (pad with (post or column or pillar))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 01:30
8	1	("6191493").PN.	USPAT	2002/06/30 01:59
9	1	6191493.URPN.	USPAT	2002/06/30 01:46
10	19	("4472730" | "5093281" | "5128746" | "5139969" | "5171716" | "5205036" | "5237013" | "5244838" | "5304460" | "5304512" | "5321303" | "5331235" | "5371044" | "5373190" | "5427938" | "5438478" | "5474958" | "6007357" | "6014318").PN.	USPAT	2002/06/30 01:47
11	1154	257/786.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:00
12	1087	257/786.ccls. and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:09
13	1045	257/786.ccls. and (@ad<20000427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:01
14	48	(257/786.ccls. and (@ad<20010427)) and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:10
15	372	257/620.ccls. and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:09
16	7	(257/620.ccls. and (@ad<20010427)) and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:52
17	8	438/462.ccls. and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:16

18	11	438/460.ccls. and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:16
19	21	438/113.ccls. and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:18
20	852	((center or middle) with (pad or trace or electrode)) and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:19
21	797	(((center or middle) with (pad or trace or electrode)) and ball and (pillar or column or post)) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:53
22	628	((((center or middle) with (pad or trace or electrode)) and ball and (pillar or column or post)) and (@ad<20010427)) and (device or chip or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:53
23	1	("6191493").PN.	USPAT	2002/06/30 02:51
24	32051	(step or stepped) with (molding or mold or encapsulant or rein)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:52
25	811	((step or stepped) with (molding or mold or encapsulant or rein)) and ball and (pillar or column or post)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:53
26	766	(((step or stepped) with (molding or mold or encapsulant or rein)) and ball and (pillar or column or post)) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 02:53
27	494	((((step or stepped) with (molding or mold or encapsulant or rein)) and ball and (pillar or column or post)) and (@ad<20010427)) and (device or chip or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 03:05
28	2306	(dielectric or insulating or insulation) near polyimide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 03:06
29	382	((dielectric or insulating or insulation) near polyimide) and 257/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 03:07

L Number	Hits	Search Text	DB	Time stamp
1	899	257/787.ccls.	USPAT	2002/06/30 13:43
2	810	257/787.ccls. and (@ad<20000423)	USPAT	2002/06/30 14:22
3	0	(stepped adj shape) near encapsulant	USPAT	2002/06/30 14:10
4	0	(stepped adj shape) with encapsulant	USPAT	2002/06/30 14:09
5	2	(stepped adj shape) near (encapsulant or mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 14:13
6	0	(stepped adj shape) with encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 14:16
7	1	("6351030").PN.	USPAT	2002/06/30 14:21
8	45	(remove or cut) near encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 14:25
9	36	((remove or cut) near encapsulant) and (@ad<20000428)	USPAT	2002/06/30 14:26
10	273	(remove or cut) with (encapsulant or (moldong adj resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/30 14:25
11	192	((remove or cut) with (encapsulant or (moldong adj resin))) and (@ad<20000428)	USPAT	2002/06/30 14:26